



High Performance Graphene Based Thermal Interface Material and Heatspreader Hybrid

Feature:

- Low thermal resistance
- Easy to use
- High bulk thermal conductivity

Applications:

IGBT, GPU, CPU, LED, RF, Opto and power module cooling

Order status: Small amount available now (□ 100 pieces)

Description:

GT80 has the highest bulk through-plane thermal conductivity among all the other competitive products, and even outperforms copper by 250%. Upon certain pressure, GT80 can provide complete physical contact between two surfaces, therefore, lead to superior effective thermal conductivity of 80 W/mK and minimum thermal resistance of 5 Kmm²/W

Physical Properties	Value		Units	Test Method
Size	□ 3*3		cm ²	
Thickness	0.25-5(± 15%)		mm	
Roughness	<5		%	
Color	Grey			
Filler Material	Graphene			
Density	1.8-2		g/cm ³	
Compressibility	5-10		%	ASTM
Recovery	5-8		%	ASTM
Compressive Strength	2-2.5		MPa	ASTM
Temperature Range	-40 to 200		°C	
Bulk Through-plane Thermal Conductivity	880-1000		W/mK	LFA447
Effective Through-plane Thermal Conductivity	7-10 (400 KPa)	75-80 (2 MPa)	W/mK	ASTM
Thermal Resistance	50-80 (400 KPa)	5-8 (2 MPa)	Kmm ² /W	ASTM
Bulk In-plane (parallel to alignment) Thermal Conductivity	880-1000		W/mK	LFA447
Bulk In-plane (perpendicular to alignment) Thermal Conductivity	5		W/mK	LFA447
Specific Heat	0.6-0.7		J/g.K	Hotdisk
Minimum tensile strength at in-plane direction	50		KPa	ASTM

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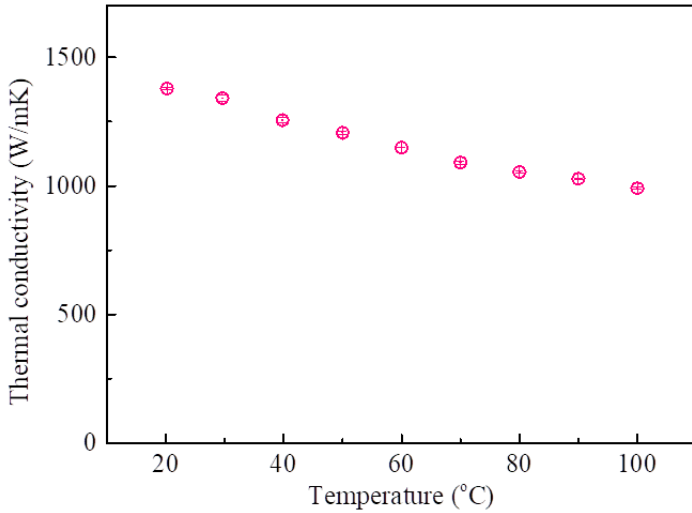
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Bulk thermal conductivity of GT80 at different temperature



Thermal resistance curve of GT80 at different pressures.

